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# 4-Bit 100 Mb/s Configurable Dual-Supply Level Translator

# **NLSX5004, NLSXN5004**

The NLSX5004 and NLSXN5004 are 4-bit configurable dual-supply autosensing bidirectional level translators that do not require direction control pins. The A- and B-ports are designed to track two different power supply rails,  $V_{CCA}$  and  $V_{CCB}$  respectively. Both the  $V_{CCA}$  and the  $V_{CCB}$  supply rails are independently-configurable from 0.9 V to 3.6 V.

The NLSX5004 and NLSXN5004 have high dynamic output current capability, allowing the translators to drive high capacitive loads.

Enable input pins are available to reduce the power consumption. These pins may be used to disable both A– and B–ports by putting them in 3–state significantly reducing the supply current from both  $V_{CCA}$  and  $V_{CCB}$ . These pins are referenced to the  $V_{CCA}$  supply. The NLSX5004 has an active–High enable (EN) while the NLSXN5004 has active–Low enable ( $\overline{EN}$ ).

#### Features

- Wide V<sub>CCA</sub>, V<sub>CCB</sub> Operating Range: 0.9 V to 3.6 V
- $V_{CCA}$  and  $V_{CCB}$  are independent -  $V_{CCA}$  may be greater than, equal to, or less than  $V_{CCB}$
- High 100 pF Capacitive Drive Capability
- High–Speed w/ 140 Mbps Guaranteed Date Rate for V<sub>CCA</sub>, V<sub>CCB</sub> > 1.8 V
- Low Bit-to-Bit skew
- Overvoltage Tolerant Enable and I/O Pins
- Non-preferential Power-Up Sequencing
- Partial Power-Off Protection
- Available packaging: UQFN-12, SOIC14, TSSOP14, QFN-14, Other packages
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and RoHS Compliant

#### **Typical Applications**

• Mobile Phones, Infotainment Systems, Other Devices

#### Important Information

 ESD Protection for All Pins: HBM (Human Body Model) – 2000 V



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	MARKING DIAGRAMS
UQFN12 MU SUFFIX CASE 523AE	A2M ○ ■
14 SOIC14 D SUFFIX CASE 751A	14 R R R R R R R XXXXXXXXG AWLYWW 18 8 8 8 8 8
14 TSSOP14 DT SUFFIX CASE 948G	14 HHHHHH XXXX XXXX ALYW- 0 1 HHHHHHH
QFN14 MN SUFFIX CASE 485DE	° XXXX AYW •
QFN14 MN SUFFIX CASE 485AL	O XXXXX XXXXX ALYW• •
$M = Date$ $A = Asset$ $L or WL = Wafe$ $Y = Year$ $W or WW = Wor$ $G or \bullet = Pb-F$	embly Location er Lot rk Week Free Package
(Note: Microdot may I	be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 11 of this data sheet.

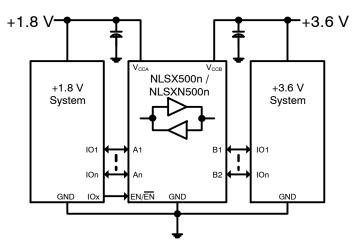


Figure 1. Typical Application Circuit

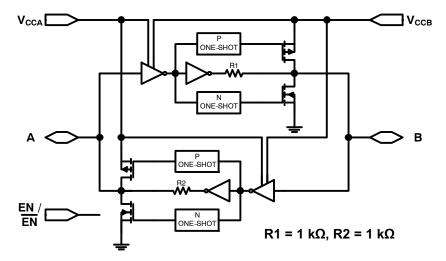


Figure 2. Functional Diagram (1 I/O Line)

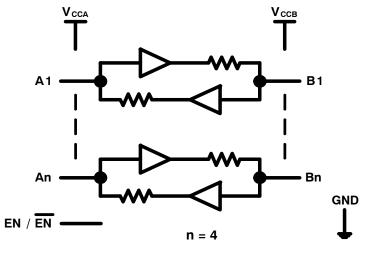


Figure 3. Logic Diagram

#### **PIN ASSIGNMENTS**

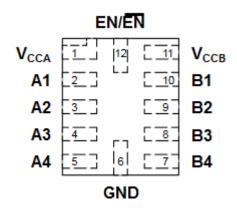


Figure 4. UQFN12

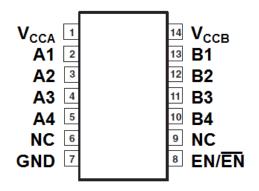


Figure 6. TSSOP / SOIC

#### **PIN DESCRIPTIONS**

Pins	Description
V <sub>CCA</sub>	A-Port Supply Voltage
V <sub>CCB</sub>	B-Port Supply Voltage
GND	Ground
EN	Active–High Enable (NLSX500n), Referenced to V <sub>CCA</sub>
EN	Active-Low Enable (NLSXN500n), Referenced to V <sub>CCA</sub>
An	A-Port, Referenced to V <sub>CCA</sub>
Bn	B-Port, Referenced to V <sub>CCB</sub>

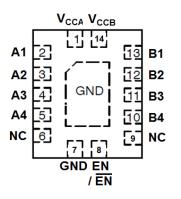


Figure 5. QFN14 (2.5 x 3.0)

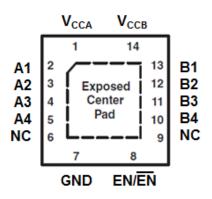


Figure 7. QFN14 (3.5 x 3.5)

FUNCTION TABLE

NLSX500n	NLSXN500n	Operating
EN	EN	Mode
L	Н	An and Bn at Hi–Z
Н	L	An and Bn Connected

#### Table 1. MAXIMUM RATINGS

Symbol	Parameter		Value	Condition	Unit
V <sub>CCA</sub>	A-side DC Supply Voltage	y Voltage			V
V <sub>CCB</sub>	B-side DC Supply Voltage	DC Supply Voltage			V
V <sub>IN</sub>	Input/Output Voltage EN/EN		-0.5 to +4.6		V
	Power Down Mode (V <sub>CCA</sub> and/or	-0.5 to +4.6			
	Tri-State Mode (EN = I	L or $\overline{EN} = H$ )	-0.5 to +4.6		
	Active Mode	A-Port	–0.5 to V <sub>CCA</sub> +0.5		
		B-Port	-0.5 to V <sub>CCB</sub> +0.5		
I <sub>IK</sub>	DC Input Diode Current		-50	V <sub>IN</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current		-50	V <sub>O</sub> < GND	mA
I <sub>CCA</sub>	DC Supply Current Through V <sub>CCA</sub>		±100		mA
I <sub>CCB</sub>	DC Supply Current Through V <sub>CCB</sub>	Current Through V <sub>CCB</sub>			mA
I <sub>GND</sub>	DC Ground Current Through Ground Pin	Current Through Ground Pin			mA
T <sub>STG</sub>	Storage Temperature	age Temperature			°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### Table 2. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V <sub>CCA</sub>	A-Port Supply Voltage		0.9	3.6	V
V <sub>CCB</sub>	B-Port Supply Voltage		0.9	3.6	V
VI	Input/Output Voltage	GND	3.6	V	
	Power Down Mode (V <sub>CCA</sub> and/or V	/ <sub>CCB</sub> = 0 V)	GND	3.6	
	Tri-State Mode (EN = L	or $\overline{EN} = H$ )	GND	3.6	
	Active Mode	A-Port	GND	V <sub>CCA</sub>	
		B-Port	GND	V <sub>CCB</sub>	
T <sub>A</sub>	Operating Temperature Range	•	-40	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate $V_{I}$ from 30% to 70% of $V_{CCA}\!/V_{CCB}$		0	10	nS

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### **Table 3. DC ELECTRICAL CHARACTERISTICS**

						-4	0°C to +85	5°C	-40°C to +125°C		
Symbol	Parameter	Test Conditions (Note 1)	Pin/Port	V <sub>CCA</sub> (V)	V <sub>CCB</sub> (V)	Min	Typ (Note 2)	Max	Min	Max	Unit
V <sub>IH</sub>	Input HIGH Voltage		A, EN/EN	0.9–3.6	0.9–3.6	0.65 * V <sub>CCA</sub>	-	-	0.65 * V <sub>CCA</sub>	-	V
			В	0.9–3.6	0.9–3.6	0.65 * V <sub>CCB</sub>	-	-	0.65 * V <sub>CCB</sub>	-	V
V <sub>IL</sub>	Input LOW Voltage		A, EN/EN	0.9–3.6	0.9–3.6	-	-	0.35 * V <sub>CCA</sub>	-	0.35 * V <sub>CCA</sub>	V
			В	0.9–3.6	0.9–3.6	-	-	0.35 * V <sub>CCB</sub>	-	0.35 * V <sub>CCB</sub>	V
V <sub>OH</sub>	Output HIGH Voltage	I <sub>OH</sub> = -20 μA	A	0.9–3.6	0.9–3.6	0.9 * V <sub>CCA</sub>	-	-	0.9 * V <sub>CCA</sub>	-	V
			В	0.9–3.6	0.9–3.6	0.9 * V <sub>CCB</sub>	_	-	0.9 * V <sub>CCB</sub>	-	V
V <sub>OL</sub>	Output LOW	I <sub>OL</sub> = 20 μA	A	0.9–3.6	0.9–3.6	-	-	0.2	-	0.2	V
	Voltage		В	0.9–3.6	0.9–3.6	-	-	0.2	-	0.2	V
I <sub>OZ</sub>	Tristate Output	$(EN = 0V \text{ or } \overline{EN} = V_{CCA});$			•		•				μA
	Leakage	$(A = 0 V \text{ or } V_{CCA})$	A	0.9–3.6	0.9–3.6	-	0.01	±1.5	-	±4.5	
		$(B = 0 V \text{ or } V_{CCB})$	В	0.9–3.6	0.9–3.6	-	0.01	±1	-	±3.5	
I	Input Pin Leakage	$V_{IN} = 0 V$ to $V_{CCA}$	EN/EN	0.9–3.6	0.9–3.6	-	0.01	±1	-	±3	μΑ
I <sub>CC</sub>	Supply Current	$(EN = V_{CCA} \text{ or } \overline{EN} = 0 \text{ V});$	V <sub>CCA</sub>	0.9–3.6	0.9–3.6	-	0.4	2.0	-	6.0	μA
		$I_{O} = 0 A$ , $(A = 0 V, B = 0 V)$ or $(A = V_{CCA}, B = V_{CCB})$	V <sub>CCB</sub>	0.9–3.6	0.9–3.6	-	0.3	1.5	-	6.0	
I <sub>CCZ</sub>	Tristate Output	$(EN = 0V \text{ or } \overline{EN} = V_{CCA}),$	V <sub>CCA</sub>	0.9–3.6	0.9–3.6	-	0.2	1.5	-	7.0	μA
	Mode Supply Current	(A = 0 V, B = 0 V)  or $(A = V_{CCA}, B = V_{CCB})$	V <sub>CCB</sub>	0.9–3.6	0.9–3.6	-	0.2	1.5	-	6.0	
I <sub>OFF</sub>	Power Off	A = 0  to  3.6  V,	A, B	0	0	-	0.02	1.5	-	5.0	μA
	Leakage	B = 0 to 3.6 V		0.9–3.6	0	-	0.01	1.5	-	5.0	1
				0	0.9–3.6	-	0.01	1.5	-	5.0	1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
Normal test conditions are V<sub>I</sub> = 0 V, C<sub>LA</sub> ≤ 15 pF and C<sub>LB</sub> ≤ 15 pF, unless otherwise specified.
Typical values are for T<sub>A</sub> = +25°C. All units are production tested at T<sub>A</sub> = +25°C. Limits over the operating temperature range are guaranteed by design.

#### **Table 4. TIMING CHARACTERISTICS**

						-40	0°C to +85	5°C	-40°C to	o +125°C	
Symbol	Parameter	Test Conditions (No	ote 3)	V <sub>CCA</sub> (V)	V <sub>CCB</sub> (V)	Min	<b>Typ</b> (Note 4)	Max	Min	Мах	Unit
				0.9–3.6	0.9–3.6	-	8.8	30	-	35	
				1.2	1.8	-	7.3	9	-	9	
				1.8	1.2	-	9.9	12	-	12	
			A to D	1.8	2.8	-	4.9	7	-	7	
			A to B	2.8	1.8	-	5.8	7.5	-	7.5	
				1.8	3.3	-	4.6	6	-	6	
				3.3	1.8	-	5.7	7	-	7	
		C <sub>L</sub> = 15 pF		1.8–3.6	1.8–3.6	-	4.3	9.5	-	10	
		0L = 10 pi		0.9–3.6	0.9–3.6	-	8.8	30	-	35	
				1.2	1.8	-	9.9	12	-	12	
				1.8	1.2	-	7.3	9	-	9	
			B to A	1.8	2.8	-	5.8	7.5	-	7.5	
			DION	2.8	1.8	-	4.9	7	-	7	
				1.8	3.3	-	5.7	7	-	7	
				3.3	1.8	-	4.6	6	-	6	
				1.8–3.6	1.8–3.6	-	4.3	9.5	-	10	
				0.9–3.6	0.9–3.6	-	9.1	32	-	35	
				1.2	1.8	-	7.8	9.3	-	9.3	
		C <sub>L</sub> = 30 pF	A to B	1.8	1.2	-	10.8	12.6	-	12.6	
				1.8	2.8	-	6.2	7.4	-	7.4	
				2.8	1.8	-	6.0	7.9	-	7.9	
				1.8	3.3	-	6.1	7.4	-	7.4	
				3.3	1.8	-	4.2	6.5	-	6.5	
t <sub>PD</sub>	Propagation Delay			1.8–3.6	1.8-3.6	-	4.5	10	-	10.5	
10				0.9-3.6	0.9–3.6	-	9.1	32	-	35	
				1.2	1.8	-	10.8	12.6	-	12.6	
				1.8	1.2	-	7.8	9.3	-	9.3	
			B to A	1.8	2.8	-	6.0	7.9	-	8.0	
				2.8	1.8	-	6.2	7.4	-	7.4	
				1.8	3.3	-	4.2	6.5	-	6.5	_
				3.3	1.8	-	6.1	7.4	-	7.4	_
				1.8–3.6 0.9–3.6	1.8-3.6	-	4.5	10	-	10.5	
				1.2	0.9–3.6 1.8	-	9.4 8.1	35 9.5	-	37 9.5	
				1.2	1.8	-	11.1	13.6	-	9.5 13.6	-
				1.8	2.8	-	6.5	7.6	_	7.6	_
			A to B	2.8	1.8	-	6.2	8.2	_	8.3	_
				1.8	3.3	-	6.3	7.6	_	7.6	
				3.3	1.8	_	4.3	6.6	_	6.6	
				1.8-3.6	1.8-3.6		4.3	10.3	_	10.8	-
		C <sub>L</sub> = 50 pF		0.9-3.6	0.9-3.6		9.4	35	_	37	-
				1.2	1.8		11.1	13.6	_	13.6	-
				1.2	1.8	_	8.1	9.5	_	9.5	-
				1.8	2.8	-	6.2	9.5 8.2	_	9.5 8.3	-
			B to A	2.8	1.8	-	6.5	7.6	_	7.6	-
				1.8	3.3		4.3	6.6	_	6.6	-
				3.3	1.8	-	6.3	7.6		7.6	-
			1	3.3	1.8-3.6	-	4.7	10.3	-	1.0	

Typical values are for T<sub>A</sub> = +25°C. Limits over the operating temperature range are guaranteed by design.
 Guaranteed by design.

#### Table 4. TIMING CHARACTERISTICS (continued)

						-4	0°C to +8	5°C	-40°C to	) +125°C	
Symbol	Parameter	Test Conditions (No	ote 3)	V <sub>CCA</sub> (V)	V <sub>CCB</sub> (V)	Min	<b>Typ</b> (Note 4)	Max	Min	Max	Unit
				0.9–3.6	0.9–3.6	-	9.9	-	-	-	
				1.2	1.8	-	8.4	10	-	10	
				1.8	1.2	-	11.5	14	-	14	
				1.8	2.8	-	5.5	8.3	-	8.3	
			A to B	2.8	1.8	-	6.9	8.9	-	9.0	
				1.8	3.3	-	5.1	6.7	-	6.8	
				3.3	1.8	-	6.8	8.2	-	8.2	
	Dranagation Daloy	C 100 pF		1.8–3.6	1.8–3.6	-	5.0	11	-	11.5	
t <sub>PD</sub>	Propagation Delay	C <sub>L</sub> = 100 pF		0.9–3.6	0.9–3.6	-	9.9	-	-	-	ns
				1.2	1.8	-	11.5	14	-	14	
				1.8	1.2	-	8.4	10	-	10	
			D to A	1.8	2.8	-	6.9	8.9	-	9.0	
			B to A	2.8	1.8	-	5.5	8.3	-	8.3	
				1.8	3.3	-	6.8	8.2	-	8.2	
				3.3	1.8	-	5.1	6.7	-	6.8	
				1.8–3.6	1.8–3.6	-	5.0	11	-	11.5	
				0.9–1.2		-	2.5	4.5	-	4.5	
			•	1.2-1.8		-	2.0	3.0	-	3.0	
	t <sub>R</sub> Output Rise Time trial		A	1.8–2.8	0.9–3.6	-	0.6	2.0	-	2.0	- ns
		0 45 5		2.8-3.6		-	0.5	2.5	-	2.5	
۲ <sub>R</sub>		C <sub>L</sub> = 15 pF	-		0.9–1.2	-	2.5	4.5	-	4.5	
			_		1.2-1.8	-	2.0	3.0	-	3.0	
			В	0.9–3.6	1.8-2.8	-	0.6	2.0	-	2.0	
					2.8-3.6	-	0.5	2.5	-	2.5	7
			А	0.9–1.2		-	2.5	6.0	-	6.0	- - - ns
				1.2-1.8	0.9–3.6	-	1.8	3.0	-	3.0	
				1.8-2.8		-	0.6	2.0	-	2.0	
		o		2.8-3.6		-	0.5	2.5	-	2.5	
t <sub>F</sub>	Output Fall Time trial	C <sub>L</sub> = 15 pF			0.9–1.2	-	2.5	6.0	-	6.0	
			_		1.2-1.8	-	1.8	3.0	-	3.0	
			В	0.9–3.6	1.8-2.8	-	0.6	2.0	-	2.0	
					2.8-3.6	-	0.5	2.5	-	2.5	
t <sub>SK</sub>	Channel-to-Channel Skew			0.9–3.6	0.9–3.6	-	-	0.15	-	0.15	ns
		a		0.9–3.6	0.9–3.6	50	-	-	50	-	
		C <sub>L</sub> = 15 pF		1.8-3.6	1.8-3.6	140	-	-	140	-	
				0.9–3.6	0.9–3.6	40	-	-	40	-	
		C <sub>L</sub> = 30 pF		1.8-3.6	1.8-3.6	120	_	_	120	_	1
MDR	Maximum Data Rate			0.9–3.6	0.9–3.6	30	_	_	30	_	Mbps
		C <sub>L</sub> = 50 pF		1.8-3.6	1.8-3.6	100	-	-	100	-	
		0 100 5		0.9–3.6	0.9–3.6	20	-	-	20	-	
		C <sub>L</sub> = 100 pF		1.8–3.6	1.8-3.6	60	-	-	60	-	
		$\frac{EN}{EN} = V_{CCA} \text{ or }$					•				
I <sub>I_PEAK</sub>	Input Driver Peak	A = 1 MHz Sq Wave, Amplitude = V <sub>CCA</sub>	Α	0.9–3.6	0.9–3.6	-	-	5.0	-	5.0	mA
		B = 1 MHz Sq Wave, Amplitude = V <sub>CCB</sub>	В	0.9–3.6	0.9–3.6	-	-	5.0	-	5.0	

Typical values are for T<sub>A</sub> = +25°C. Limits over the operating temperature range are guaranteed by design.
 Guaranteed by design.

#### Table 4. TIMING CHARACTERISTICS (continued)

						-4	0°C to +8	5°C	-40°C to	o +125°C	
Symbol	Parameter	Test Conditions (No	ote 3)	V <sub>CCA</sub> (V)	V <sub>CCB</sub> (V)	Min	<b>Typ</b> (Note 4)	Max	Min	Max	Unit
				0.9		1	37	-	-	-	
			А	1.8	0.9–3.6	I	20	-	-	-	
ZO	1-Shot Output			3.6		I	10	-	-	-	Ω
(Note 4)	Impedance				0.9	-	37	-	-	-	52
			В	0.9–3.6	1.8	-	20	-	-	-	
					3.6	-	10	-	-	-	
				0.9–3.6	0.9–3.6	-	116.3	200	-	200	
		C <sub>L</sub> = 15 pF; B = V <sub>CCB</sub>		1.2–1.8	1.2–1.8	-	64.5	180	-	180	
				1.8–2.8	1.8–2.8	-	49.6	150	-	150	
			EN/EN	1.8–3.6	1.8–3.6	-	42.5	100	-	100	
			to A	0.9–3.6	0.9–3.6	-	113.4	300	-	300	
		C <sub>L</sub> = 15 pF; B = 0 V		1.2–1.8	1.2–1.8	-	100	250	-	250	ns
				1.8–2.8	1.8–2.8	-	94.3	200	-	200	113
test	Output Enable Time			1.8–3.6	1.8–3.6	-	90.9	170	-	170	
t <sub>EN</sub>		$C_L = 15 \text{ pF}; \text{ A} = \text{V}_{\text{CCA}}$		0.9–3.6	0.9–3.6	-	116.3	200	-	200	
				1.2–1.8	1.2–1.8	-	64.5	180	-	180	
				1.8–2.8	1.8–2.8	I	49.6	150	-	150	
			EN/EN	1.8–3.6	1.8–3.6	-	42.5	100	-	100	
			to B 0 V	0.9–3.6	0.9–3.6	-	113.4	300	-	300	
				1.2–1.8	1.2–1.8	I	100	250	-	250	ns
				1.8–2.8	1.8–2.8	1	94.3	200	-	200	113
				1.8–3.6	1.8–3.6	-	90.9	170	-	170	
				0.9–3.6	0.9–3.6	-	255	600	-	600	
		C <sub>L</sub> = 15 pF; B = V <sub>CCB</sub>		1.2–1.8	1.2–1.8	I	180	350	-	350	
		$O_{L} = 10 \text{ pr}$ , $D = V_{CCB}$		1.8–2.8	1.8–2.8	1	166.7	350	-	350	
			EN/EN	1.8–3.6	1.8–3.6	-	155.6	300	-	300	
			to A	0.9–3.6	0.9–3.6	-	156.7	400	-	400	
		C <sub>L</sub> = 15 pF; B = 0 V		1.2–1.8	1.2–1.8	I	140	300	-	300	
		$O_{L} = 15 \text{ pr}, D = 0 \text{ v}$		1.8–2.8	1.8–2.8	1	130.2	300	-	300	
teve	Output Disable Time			1.8–3.6	1.8–3.6	-	124.6	250	-	250	ns
t <sub>DIS</sub>				0.9–3.6	0.9–3.6	I	255	600	-	600	115
		C <sub>L</sub> = 15 pF; A = V <sub>CCA</sub>		1.2–1.8	1.2–1.8	1	180	350	_	350	
		$O_L = 10 \text{ pr}, \text{A} = \text{V}_{CCA}$		1.8–2.8	1.8–2.8	-	166.7	350	_	350	
			EN/EN	1.8–3.6	1.8–3.6	-	155.6	300	-	300	
			to B	0.9–3.6	0.9–3.6	-	156.7	400	_	400	]
				1.2–1.8	1.2–1.8	-	140	300	-	300	]
		C <sub>L</sub> = 15 pF; A = 0 V		1.8–2.8	1.8–2.8	I	130.2	300	-	300	
				1.8-3.6	1.8–3.6	-	124.6	250	-	250	]

3. Typical values are for  $T_A = +25^{\circ}C$ . Limits over the operating temperature range are guaranteed by design. 4. Guaranteed by design.

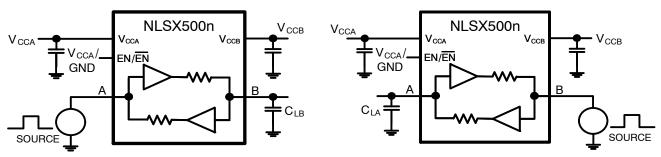




Figure 9. Driving B-Port Test Circuit (t<sub>PD</sub>)

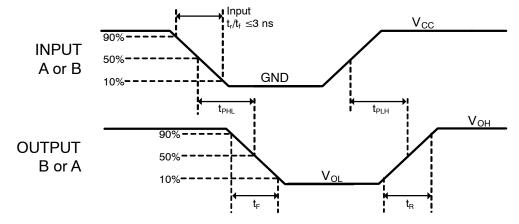


Figure 10. t<sub>PD</sub> (t<sub>PLH</sub>/t<sub>PHL</sub>) Propagation Delay Measurements

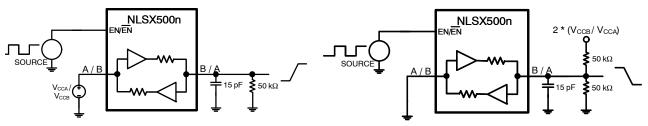


Figure 11. Enable/Disable Test Circuit (t<sub>PZH</sub>/t<sub>PHZ</sub>)



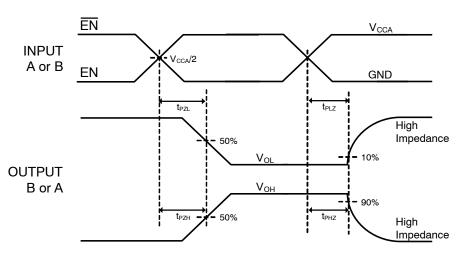


Figure 13.  $t_{\text{EN}}/t_{\text{DIS}}$  ( $t_{\text{PZL}}/t_{\text{PLZ}}/t_{\text{PZH}}/t_{\text{PHZ}}$ ) Propagation Delay Measurements

#### IMPORTANT APPLICATIONS INFORMATION

#### Level Translator Architecture

The NLSX5004 and the NLSXN5004 auto-sense translators provide bi-directional logic voltage level shifting to transfer data in multiple supply voltage systems. These level translators have two supply voltages,  $V_{CCA}$  and  $V_{CCB}$ , which set the logic levels on the input and output sides of the translator. When used to transfer data from the A to the B ports, input signals referenced to the  $V_{CCA}$  supply are translated to output signals with a logic level matched to  $V_{CCB}$ . In a similar manner, the B to A translation shifts input signals with a logic level compatible to  $V_{CCB}$  to an output signal matched to  $V_{CCA}$ .

The NLSX5004 and the NLSXN5004 translators consist of bi-directional channels that independently determine the direction of the data flow without requiring a directional pin. One-shot circuits are used to detect the rising or falling input signals. In addition, the one-shots decrease the rise and fall times of the output signal for high-to-low and low-to-high transitions.

#### Input Driver Requirements

The NLSX5004 and NLSXN5004 support high data rates, but these translators have relatively modest DC output current drive. The high data rate of the bi-directional I/O circuit is used to quickly transform from an input to an output driver and vice versa. Each I/O port has a modest DC current output so that the internal output driver can be over-driven when data is sent in the opposite direction. For proper operation, the input driver to the auto-sense translator should be capable of driving 5.0 mA of peak output current. The bi-directional configuration of the translator results in both input stages being active for a very short time period. Although the peak current required from the input signal circuit is relatively large, the average current is small and consistent with a standard CMOS input stage.

#### Enable Input (EN/EN)

The NLSX5004 and NLSXN5004 translators have enable pins that provide tri-state operation at the I/O ports.

Driving the NLSX5004 Enable pin (EN) to a low logic level minimizes the power consumption of the device and drives the A– and B–ports to high impedance states. Normal translation operation occurs when the EN pin is equal to a logic high signal.

Driving NLSXN5004 Enable pin  $(\overline{\text{EN}})$  to a high logic level minimizes the power consumption of the device and drives the A– and B–ports to high impedance states. Normal translation operation occurs when the  $\overline{\text{EN}}$  pin is equal to a logic low signal.

Both EN and  $\overline{\text{EN}}$  pins are referenced to the V<sub>CCA</sub> supply and are Over–Voltage Tolerant (OVT).

#### Uni-Directional versus Bi-Directional Translation

The NLSX5004 and NLSXN5004 translators can function as non-inverting uni-directional translators. One advantage of using these translators as uni-directional devices is that each I/O-port can be configured as either an input or an output. The configurable input or output feature is especially useful in applications such as SPI that use multiple uni-directional I/O lines to send data to and from a device. The flexible I/O port of the auto sense translator simplifies the trace connections on the PCB.

#### **Power Supply Guidelines**

The values of the  $V_{CCA}$  and  $V_{CCB}$  supplies can be set to anywhere between 0.9 and 3.6 V. Design flexibility is maximized because  $V_{CCA}$  may be either greater than, equal to or less than the  $V_{CCB}$  supply.

The sequencing of the power supplies will not damage the device during power-up operation. In addition, the Aand B-ports are in high impedance states if either supply voltage is equal to 0 V. For optimal performance, 0.01 to  $0.1 \,\mu\text{F}$  decoupling capacitors should be used on the V<sub>CCA</sub> and V<sub>CCB</sub> power supply pins. Ceramic capacitors are a good design choice to filter and bypass any noise signals on the voltage lines to the ground plane of the PCB. The noise immunity will be maximized by placing the capacitors as close as possible to the supply and ground pins, along with minimizing the PCB connection traces.

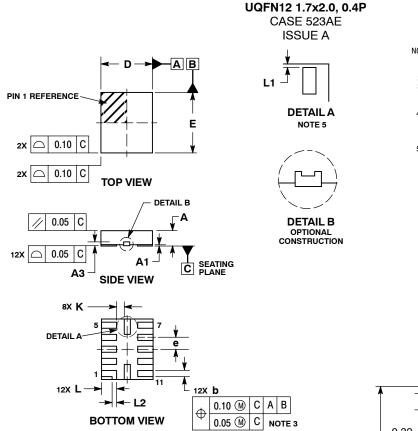
#### **DEVICE ORDERING INFORMATION**

Device Order Number	Package Type	Tape & Reel Size <sup>†</sup>
NLSX5004MUTAG	UQFN-12	3000 Units/Reel
NLVSX5004MUTAG*	UQFN-12	3000 Units/Reel
NLSX5004DR2G (In Development)	SOIC14	2500 Units/Reel
NLVSX5004DR2G* (In Development)	SOIC14	2500 Units/Reel
NLSX5004DTR2G (In Development)	TSSOP14	2500 Units/Reel
NLVSX5004DTR2G* (In Development)	TSSOP14	2500 Units/Reel
NLSX5004MN1TXG (In Development)	QFN14, 3.5 x 3.5 x 0.5P	3000 Units/Reel
NLVSX5004MN1TXG*	QFN14, 3.5 x 3.5 x 0.5P	3000 Units/Reel
NLSX5004MN1TWG (In Development)	QFN14, 2.5 x 3.0 x 0.5P	3000 Units/Reel
NLVSX5004MN1TWG* (In Development)	QFN14, 2.5 x 3.0 x 0.5P	3000 Units/Reel
NLSXN5004MU2TAG (In Development)	UQFN-12	3000 Units/Reel
NLVSXN5004MU2TAG* (In Development)	UQFN-12	3000 Units/Reel
NLSXN5004DR2G (In Development)	SOIC14	2500 Units/Reel
NLVSXN5004DR2G* (In Development)	SOIC14	2500 Units/Reel
NLSXN5004DTR2G (In Development)	TSSOP14	2500 Units/Reel
NLVSXN5004DTR2G* (In Development)	TSSOP14	2500 Units/Reel
NLSXN5004MN1TXG (In Development)	QFN14, 3.5 x 3.5 x 0.5P	3000 Units/Reel
NLVSXN5004MN1TXG* (In Development)	QFN14, 3.5 x 3.5 x 0.5P	3000 Units/Reel
NLSXN5004MN1TWG (In Development)	QFN14, 2.5 x 3.0 x 0.5P	3000 Units/Reel
NLVSXN5004MN1TWG* (In Development)	QFN14, 2.5 x 3.0 x 0.5P	3000 Units/Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

#### PACKAGE DIMENSIONS

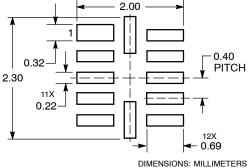


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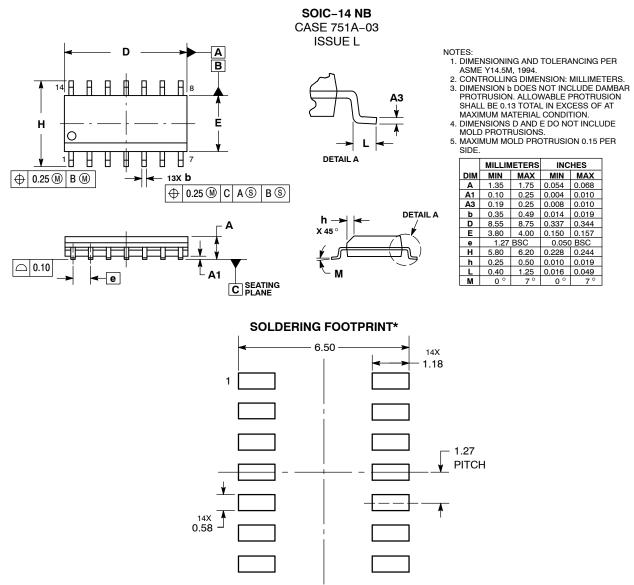
- VOIES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FORDUTE FORMUN. 201
- FROM TERMINAL TIP. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH 0.03 MAX ON BOTTOM SURFACE OF 4.
- TERMINALS.5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

	MILLIMETERS						
DIM	MIN	MAX					
Α	0.45	0.55					
A1	0.00	0.05					
A3	0.127	REF					
b	0.15	0.25					
D	1.70	BSC					
Е	2.00	BSC					
e	0.40	BSC					
Κ	0.20						
L	0.45	0.55					
L1	0.00	0.03					
L2	0.15 REF						

#### MOUNTING FOOTPRINT SOLDERMASK DEFINED



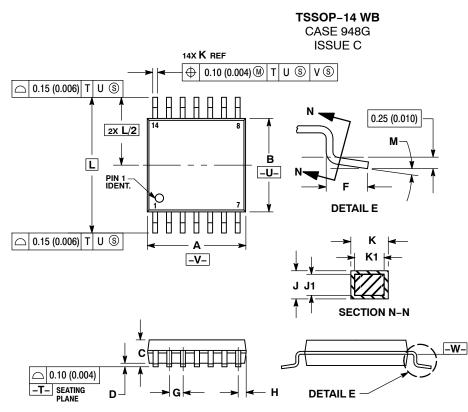
#### PACKAGE DIMENSIONS



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS



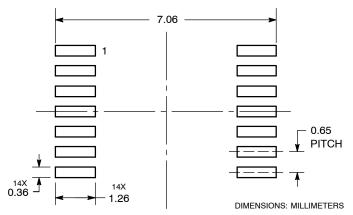
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1. DIMENSIONING AND TOLERANCING PER

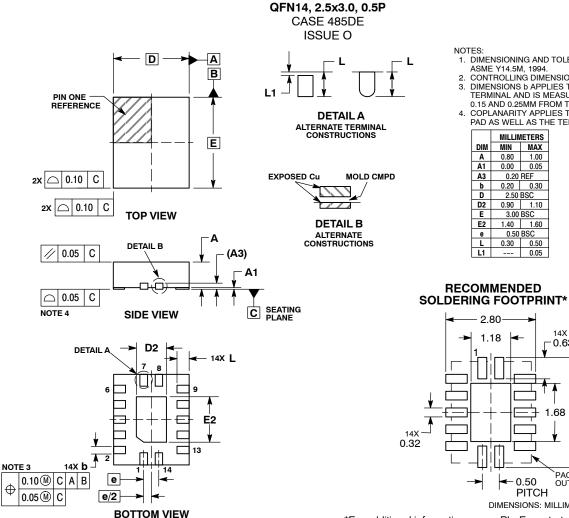
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
   DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
   DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. SIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION KLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
   TERMINAL NUMBERS ARE SHOWN FOR
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-. 6.
- 7.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
κ	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	6.40 BSC		2 BSC	
М	0 °	8 °	0 °	8 °	

SOLDERING FOOTPRINT



#### PACKAGE DIMENSIONS



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

0.50

PITCH

DIMENSIONS: MILLIMETERS

NOTES:

З.

4.

DIM A A1

A3

b D D2

Е

E2

e L

L1

2.80

1.18

DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.

DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN

PAD AS WELL AS THE TERMINALS.

MILLIMETERS

MIN MAX

 0.80
 1.00

 0.00
 0.05

0.20 REF

0.20 REF 0.20 0.30 2.50 BSC 0.90 1.10 3.00 BSC

1.40 1.60

0.30 0.50

0.05

14X

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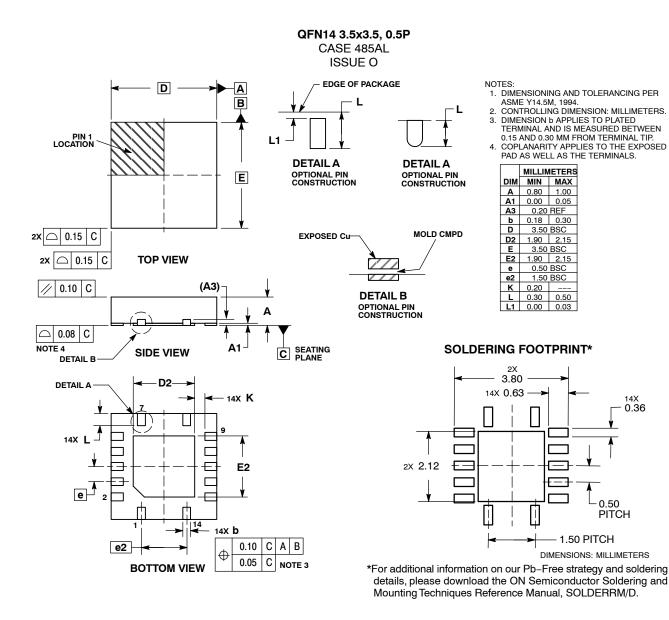
1.68 3.33

PACKAGE

0.50 BSC

0.15 AND 0.25MM FROM THE TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED

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